

TQFP (TQ/TQG 100, 144, 176 Pin) Packages and Heat Sink TQFP (HT/HTG 100, 144, 176 Pin) Packages

	TOP VIEW	0.20 C A-B	BOTTOM VIEW
			$\begin{array}{c c c c c c c c c c c c c c c c c c c $
			.20 MIN GAGE PLANE
TQ/TQG/HT/HTG100 MILLIMETERS MIN. NOM. MAX. A ~ 1.60 A1 0.05 ~ 0.15 A2 1.35 1.40 1.45 D/E 16.00 BSC 0.75 0.050 BSC D1/E1 0.45 0.60 0.75 0.20 C 0.09 ~ 0.20 0.20 Cccc ~ ~ 0.08 0.08 ddd ~ 0.08 0.08 0.08	TQ/TQG/HT/HTG144 MILLIMETERS MIN. NDM. MAX. MIN. NDM. MAX. MAX. MIN. NDM. MAX. MAX. MIN. NDM. MAX. MAX. MIN. NDM. NDM. NL40 0.15 1.40 1.45 22.00 BSC 0.60 0.17 0.22 0.20 20 MIT 0.08 MIT 0.08 MIT 0.08 MIT 144	TQ/TQG/HT/HTG176 MILLIMETERS MIN. NDM. MAX. ~ ~ 1.60 0.05 0.10 0.15 1.40 1.35 1.40 26.00 BSC 24.00 BSC 0.45 0.60 0.75 0.50 BSC 0.17 0.22 0.27 0.09 ~ 0.20 ~ 0.08 ~ ~ 0.08 ~ 176 176	DETAIL 'A' NOTE: 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5-1994 2. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE. 3. PACKAGE TOP DIMENSION MAY BE SMALLER THAN THE BOTTOM DIMENSION MAY BE SMALLER THAN THE BOTTOM DIMENSION BY 0.15mm. (4. THE SAME PACKAGE DIMENSIONS APPLY FOR THERMALLY ENHANCED PRODUCTS. HEAT SINK IS ADDED. THE PACKAGE CODE IS "HT". HEAT SINK DIMENSIONS: HT100=10.0mm SQ. REF. HT144=15.5mm SQ. REF. HT176=19.4mm SQ. REF.
REF. JEDEC MS-026-BED	JEDEC MS-026-BFB	JEDEC MS-026-BGA	✓5\ MARK ORIENTATION WITH RESPECT TO PIN-1 LD. IF 2 OR MORE CIRCLES EXIST ON TOP OF THE PACKAGE, USE THE SMALLEST CIRCLE AS PIN-1 LD.

100, 144, and 176-PIN TQFP (TQ100/TQG100, TQ144/TQG144, and TQ176/TQG176) 100, 144, and 176-PIN HEAT SINK TQFP (HT100/HTG100, HT144/HTG144, and HT176/HTG176)

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